

TOSHIBA BIPOLAR LINEAR INTEGRATED CIRCUIT SILICON MONOLITHIC

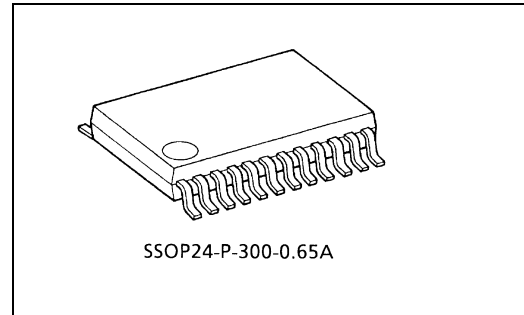
TA1384FNG

Mixer/Oscillator and PLL IC for TV/VCR Tuner

The TA1384FNG is a tuner IC for TV and VCR applications that integrates a PLL block and mixer, oscillator and IF amplifier on a single chip.

The control data of the PLL block conforms to I²C-bus formats.

Small flat package: SSOP24 (0.65 mm pitch)



Weight: 0.09 g (typ.)

Features

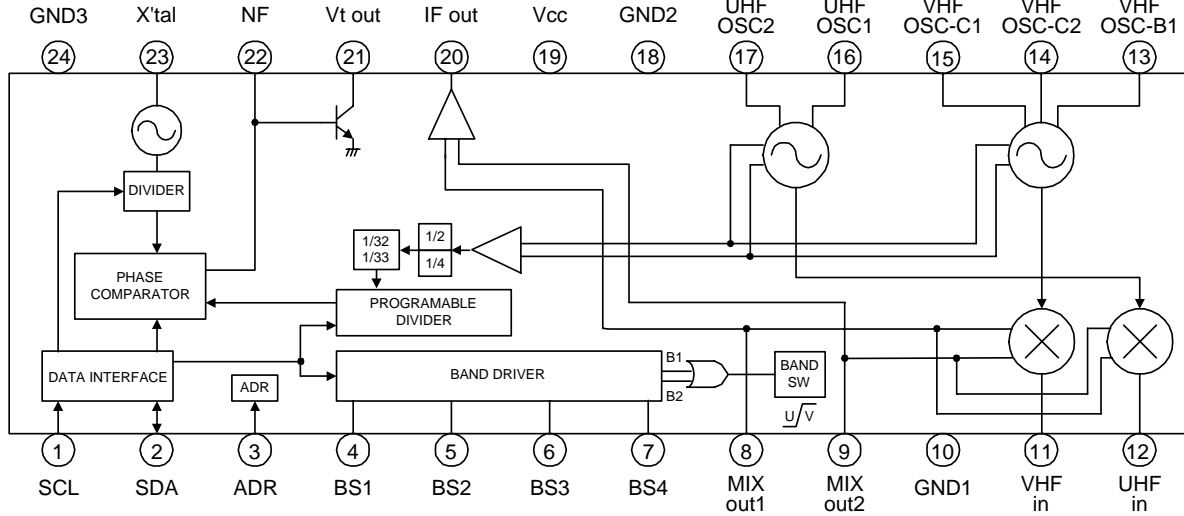
- V_{cc}: 5V (typ.)
- Two-band mixer
- Two-band oscillator
- IF output driver
- Asymmetrical IF output
- I²C bus format control
- 33-V high voltage tuning amplifier built-in
- Four-bit bandswitch drive transistor
- Frequency steps: 31.25 kHz, 50 kHz, 62.5 kHz (when a 4 MHz crystal is used)
- Four-programmable chip address
- Power on reset circuit
- Automatic changeover between 1/4 and 1/2 prescaler through data input
- Package: Pb-free

Power on reset status

- Frequency step: 62.5 kHz
- Charge pump current: Low
- Counter data: ALL [0]
- Band driver: OFF
- Tuning amplifier: OFF (Charge pump = sink mode)
- Local oscillator and mixer: UHF mode

Note 1: This device is sensitive to surge voltage and electrostatic discharge. Handle with care.

Block Diagram



Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purposes.

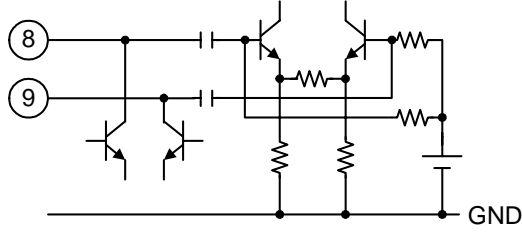
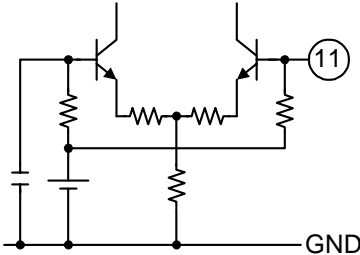
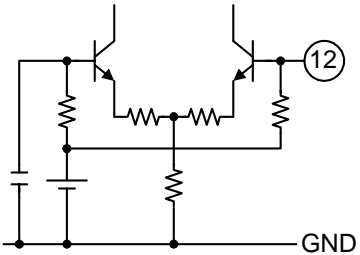
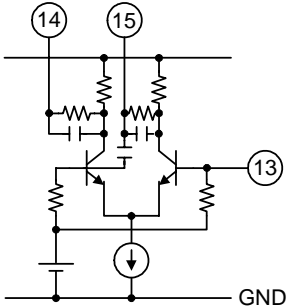
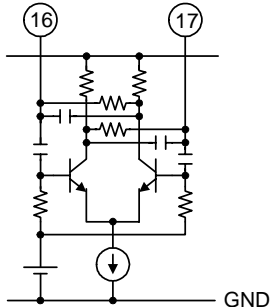
Terminal Name

Pin No.	Pin Name
1	SCL input
2	SDA in/output
3	ADR (address setting)
4	Band 1 output (VHF mode)
5	Band 2 output (VHF mode)
6	Band 3 output (UHF or FMT)
7	Band 4 output (UHF or FMT)
8	Mixer output 1
9	Mixer output 2
10	GND 1
11	VHF RF input
12	UHF RF input
13	VHF oscillator –B1
14	VHF oscillator –C2
15	VHF oscillator –C1
16	UHF oscillator 1
17	UHF oscillator 1
18	GND 2
19	Vcc
20	IF output
21	Vt output
22	NF
23	Crystal input
24	GND 3

Terminal Function

The equivalent circuit diagrams may be simplified or some parts of them may be omitted for explanatory purposes.

Pin No.	Pin Name.	Function	Interface
1	SCL	Serial clock input pin	
2	SDA	Serial data input and output pin	
3	ADR	Address setting pin The address of the PLL block is set up using the voltage applied to this pin.	
4 5 6 7	BS1 ~ BS4	The output port of the band block can be set up using the control data. Bear in mind that drive current differs according to each band drive port..	

Pin No.	Pin Name.	Function	Interface
8 9	Mixer Output	Mixer output pins A tank circuit is connected between the pins for tuning. Since these are open collector outputs, be sure to connect with a power supply through a load (resistance, coil).	
10	GND 1	Ground pin	-
11	VHF RF Input	RF signal input pin for the VHF band. Asymmetrical input type	
12	UHF RF Input	RF signal input pin for the UHF band. Asymmetrical input type	
13 14 15	VHF Oscillator	Local oscillator for the VHF band The oscillator type is symmetrical amplifier	
16 17	UHF Oscillator	Local oscillator for the UHF band The oscillator type is symmetrical amplifier.	

Pin No.	Pin Name.	Function	Interface
18	GND 2	Ground pin	—
19	Vcc	Power supply pin	—
20	IF Output	IF signal output pin Asymmetrical output type. Output impedance is about 75 Ω.	
21	Vt Output	<p>Be sure to connect a resistance (of about 33 kΩ) between pin 21 and the 33-V external power supply for tuning.</p> <p>To prevent abnormal oscillation, connect between pin 21 and GND a capacity element that does not affect a PLL.</p>	
22	NF		
23	Crystal Input	Crystal oscillator input pin A 4-MHz crystal is used.	
24	GND 3	Ground pin	—

Maximum Ratings

CHARACTERISTIC	PIN No	SYMBOL	RATING	UNIT
Vcc	19	Vcc	6	V
Tuning Amplifier Voltage Applied	21	VBT	38	V
Bus Data Voltage Applied	1, 2	SDA,SCL	-0.3~6	V
Pin for DC Voltage Applied Except for GND and the Above Pins	-	VIN	-0.3~Vcc+0.3	V
RF Signal Input Level for Mixer	11,12	fin	120	dBuV
Power Dissipation	-	PD	890 (Note 3)	mW
Operating Temperature	-	Topr	-20~85	°C
Storage Temperature	-	Tstg	-55~150	°C

Note 2: The absolute maximum ratings of a semiconductor device are a set of specified parameter values that must not be exceeded during operation, even for an instant.

If any of these rating are exceeded during operation, the electrical characteristics of the device may be irreparably altered, in which case the reliability and lifetime of the device can no longer be guaranteed.

Moreover, any exceeding of the ratings during operation may cause breakdown, damage and/or degradation in other equipment.

Applications using the device should be designed so that no maximum rating will ever be exceeded under any operating conditions.

Before using, creating and/or producing designs, refer to and comply with the precautions and conditions set forth in this documents.

Note 3: 50 × 50 × 1.6 mm, Cu 40% board used.

When using the device at above Ta = 25°C, decrease the power dissipation by 7.2 mW for each increase of 1°C.

Operating Supply Voltage

Pin No.	SYMBOL	MIN.	TYP.	MAX.	UNIT
19	Vcc	4.5	5.0	5.5	V

Electric Characteristics

DC Characteristics

(Unless otherwise specified, Vcc = 5 V, Ta = 25°C)

CHARACTERISTICS	SYMBOL	TEST CIRCUIT	BAND	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Power Supply and Current	Icc1	1	VHF	Bus data B1 = ON, (pin 4: Open)	49	62	75	mA
	Icc2		UHF	Bus data B4 = ON, (pin 7: Open)	52	65.5	79.5	

MIX / OSC / IF Block

(Unless otherwise specified, Vcc = 5 V, Ta = 25°C)

CHARACTERISTICS	SYMBOL	TEST CIRCUIT	BAND	TEST CONDITION (Notes 4 & 5)	MIN.	TYP.	MAX.	UNIT
Conversion Gain (see 1)	CG	2	VHF	RF = 55.25 MHz -30 dBmWin	20.5	23.5	26.5	dB
			VHF	RF = 367.25 MHz -30 dBmWin	21.5	24.5	27.5	
			UHF	RF = 373.25 MHz -30 dBmWin	25.0	28.0	31.0	
			UHF	RF = 801.25 MHz -30 dBmWin	25.5	28.5	31.0	
Noise Figure (see 2)	NF	3	VHF	RF = 55.25 MHz	-	11.0	-	dB
			VHF	RF = 367.25 MHz	-	10.0	-	
			UHF	RF = 373.25 MHz	-	8.0	-	
			UHF	RF = 801.25 MHz	-	8.0	-	
IF Output Power Level (see 3)	Ifp	2	VHF	RF = 55.25 MHz	8.5	10	-	dBmW
			VHF	RF = 367.25 MHz	8.5	10	-	
			UHF	RF = 373.25 MHz	8.5	10	-	
			UHF	RF = 801.25 MHz	8.5	10	-	
Conversion Gain Shift (see 4)	CGs	2	VHF	RF = 55.25 MHz -30 dBmWin	-	-	± 0.5	dB
			VHF	RF = 367.25 MHz -30 dBmWin	-	-	± 0.5	
			UHF	RF = 373.25 MHz -30 dBmWin	-	-	± 0.5	
			UHF	RF = 801.25 MHz -30 dBmWin	-	-	± 0.5	
Frequency Shift (The PLL is not operating.) (see 5)	ΔfB	2	VHF	OSC = 101 MHz	-	± 100	-	kHz
			VHF	OSC = 413 MHz	-	± 300	-	
			UHF	OSC = 419 MHz	-	± 200	-	
			UHF	OSC = 847 MHz	-	± 800	-	
1% Cross Modulation (see 6)	CM	4	VHF	fd = 55.25 MHz -30 dBmWin	-	88	-	dBuV
			VHF	fd = 367.25 MHz -30 dBmWin	-	84	-	
			UHF	fd = 373.25 MHz -30 dBmWin	-	83	-	
			UHF	fd = 801.25 MHz -30 dBmWin	-	81	-	
3 rd Inter Modulation for MOP block (see 7)	IM3	4	VHF	fd = 55.25 MHz -35 dBmWin	-	74	-	dB
			VHF	fd = 367.25 MHz -35 dBmWin	-	70	-	
			UHF	fd = 373.25 MHz -35 dBmWin	-	62	-	
			UHF	fd = 801.25 MHz -35 dBmWin	-	61	-	
6ch beat (see 8)	B6	4	VHF	fp = 83.25 MHz, fs = 87.75 MHz -30 dBmW input	-	62	-	dB

Note 4: IF output frequency: 45.75 MHz

Note 5: IF output load: 75 Ω

PLL / Band Block

(Unless otherwise specified, Vcc = 5 V, Ta = 25°C)

CHARACTERISTICS	SYMBOL	TEST CIRCUIT	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Band Port Drive Current	IBD-1	1	Pin 4, maximum drive current	-	-	7	mA
	IBD-2		Pin 5, maximum drive current	-	-	10	
	IBD-3		Pin 6, maximum drive current	-	-	3	
	IBD-4		Pin 7, maximum drive current			7	
Band Port Drive Maximum Current	IBDmax	1	Maximum drive current / 2 port ON	-	-	17	mA
Band Port Drive Voltage Drop	VBDsat	1	With each port at maximum current drive. 1 port ON	-	0.15	0.2	V
Tuning Amplifier Output Voltage (Close Loop)	Vt out	3	Isink = 1.5 mA	0.3	-	33	V
Tuning Amplifier Maximum Current	Ivt	3	VBT = 33 V	-	-	1.5	mA
Crystal Negative Resistance	XtR	1	4-MHz crystal used	1	2	-	kΩ
Crystal Operating Range	Xo fin	1	-	-	4	-	MHz
Crystal External Input Level	Xo extl	2	Ref. freq. = 4 MHz input	-	400	-	mVp-p
Ratio Setting Range	N	-	15-bit counter	1024	-	32767	Ratio
Logic Input Low Voltage	VBsL	1	SDA, SCL pin	-0.3	-	1.5	V
Logic Input High Voltage	VBsH	1	SDA, SCL pin	2.7	-	Vcc +0.3	V
Logic Input Current (Low)	I BsL	1	SDA, SCL pin	-20	-	10	uA
Logic Input Current (High)	I BsH	1	SDA, SCL pin	-10	-	20	uA
Charge Pump Output Current	Ichg	1	CP = 0	±40	±55	±70	uA
			CP = 1	±190	±250	±310	
ACK Output Voltage	VACK	1	ISINK = 3 mA	-	-	0.4	V

The range of the crystal external input level (Xo extl) in the internal circuit configuration is 300 – 650 mVp-p (when a signal of 4 MHz is applied).

I²C Bus Line Characteristic

CHARACTERISTICS	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
SCL Clock Frequency	f _{scl}		0	-	400	kHz
Bus Free Time between a STOP and a START Condition	t _{BUF}		1.3	-	-	μs
Hold Time (Repeated) START Condition	t _{HD;STA}		0.6	-	-	μs
Low Period of the SCL Clock	t _{LOW}		1.3	-	-	μs
High Period of the SCL Clock	t _{HIGH}		0.6	-	-	μs
Set-up Time for a Repeated START Condition	t _{SU;STA}		0.6	-	-	μs
Data Hold Time	t _{HD;DAT}		0	-	0.9	μs
Data Set-up Time	t _{SU;DAT}		100	-	-	μs
Rise Time of both SDA and SCL Signal	t _R		-	-	300	μs
Fall Time of both SDA and SCL Signals	t _F		-	-	300	μs
Set up Time for STOP Condition	t _{SU;STO}		0.6	-	-	μs

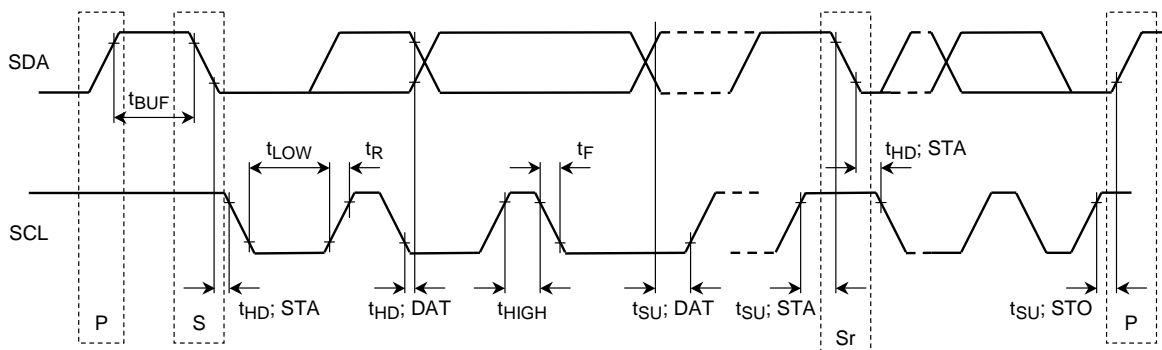


Figure 1: I²C-bus data timing chart (falling edge timing)

Timing charts may be simplified for explanatory purposes.

Test Conditions

Conversion Gain (see 1)

RF Input level = -30dBmW (untuned)

Noise Figure (see 2)

Noise figure meter used. Direct reading. (DSB)

IF Output Power Level (see 3)

Measure IF output level when it is maximum level.

Conversion Gain Shift (see 4)

The conversion gain shift is defined as a change in conversion gain when supply voltage varies from $V_{cc} = 5\text{ V}$ to 4.5 V or from $V_{cc} = 5\text{ V}$ to 5.5 V .

Frequency Shift (the PLL is not operating) (see 5)

The frequency shift is defined as a change in oscillator frequency when supply voltage varies from $V_{cc} = 5\text{ V}$ to 4.5 V or from $V_{cc} = 5\text{ V}$ to 5.5 V .

1% Cross Modulation (see 6)

- $f_d = f_p$: (f_d input level = -30dBmW)
- $f_{ud} = f_p \pm 12\text{MHz}$, 100 kHz AM30%

Input two signals, and increase the f_{ud} input level.

Measure the f_{ud} input level when the suppression level reaches 56.5dB.

3rd Internal Modulation (see 7)

- $f_d = f_p$: (f_d Input level = -35dBmW)
- $f_{ud} = f_p \pm 1\text{ MHz}$: (f_{ud} input level = -35dBmW)

Input two signals, measure the suppression level.

6-ch beat (see 8)

- $f_p = 83.25\text{MHz}$: (input level = -30 dBmW)
- $f_s = 87.75\text{MHz}$: (input level = -30 dBmW)

Input two signals, measure the suppression level of the IF / undesired signal.

*Undesired signal = $(f_p + f_s) - f_{osc} = (83.25 + 87.75) - 129 = 42\text{ MHz}$.

Description of PLL Block Operation

- I²C bus control -

The TA1384FNG conforms to the I²C-bus format.

I²C-bus mode enables two-way bus communications with Write Mode, which receives data, and Read Mode, which sends data.

Write Mode and Read Mode are set using the last bit (R/W bit) of the address byte. If the last address bit is set to [0], Write Mode is selected; if it is set to [1], Read Mode is selected.

Addresses can be set using the hardware bits, and four programmable addresses are available. With this setting, multiple frequency synthesizers can be used in the same I²C-bus. The address for the hardware bit setting can be selected by applying voltage to the address setting pin (ADR: pin 3). An address is selected according to the set bits.

If the correct address bytes are received, the serial data (SDA) line is "Low" during acknowledgment; when Write Mode is set, the serial data (SDA) line is "Low" during the next acknowledgment if the data byte is programmed. The IC is equipped with 1/2 and 1/4 built-in prescalers, and it is possible to change from one prescaler to the other using input data.

When a frequency step of 62.5 kHz is selected, the 1/2 prescaler operates with a divider ratio of 1024 to 4095, and the 1/4 prescaler operates with a divider ratio of 4096 to 32767.

When the frequency step selected is 31.25 kHz and 50 kHz, the 1/2 prescaler operates with a divider ratio of 1024 to 8191, and the 1/4 prescaler operates with a divider ratio of 8192 to 32767.

In addition, even if the prescaler is changed, the data is calculated in the internal circuit and is processed so that the comparison frequency in each the frequency step does not change.

For a frequency step of 62.5 kHz: 15.625 kHz comparison frequency

For a frequency step of 50 kHz: 12.5 kHz comparison frequency

For a frequency step of 31.25 kHz: 7.8125 kHz comparison frequency

This IC incorporates a built-in power-on reset circuit for which a detection voltage of approximately 1.4 V has been set. When the V_{cc} is supplied, a delay or stoppage in a power supply voltage close to this detection voltage may cause the power-on reset circuit to malfunction, in which case there is a risk that some data may not be received even after the recommended voltage has been restored.

A) Write Mode (Setting Command)

When WRITE mode is set so that the different types of information may be received, byte 1 is used to specify the address data; byte 2 and byte 3, the frequency data; byte 4, function setting data such as the divider ratio setting; and byte 5, the output port data (bandswitch data).

Data are latched and transferred one after the other in the case of byte 3, byte 4 and byte 5, while byte 2 and byte 3 are latched and transferred as a two-byte set (byte 2 + byte 3).

Once a correct address is received and acknowledged, the data type is determined by whether the first bit of the next byte is set to [0] or [1]. [0] indicates frequency data, while [1] indicates function setting or output data.

Until the I²C-bus STOP CONDITION is detected, the additional data can be input without transmitting the address data again. (For example: Frequency sweep is possible with additional frequency data.)

If data transmission is aborted, data programmed before the abort are valid.

BYTE 1

Hardware bit setting of byte 1 is possible using the address data.

The hardware bit is set with the voltage applied to the address-setting pin (ADR: pin 3).

BYTE 2, BYTE 3

Byte 2, byte 3 are stored in the 15-bit shift register with counter data for the frequency setting, and control the 15-bit programmable counter ratio.

The program frequency can be calculated in the following formula:

$$f_{osc} = 4 \times fr \times N.$$

f _{osc}	: Program frequency
4	: Prescaler
fr	: Phase comparator reference frequency (step frequency)
N	: Counter total divider ratio

fr is calculated using the crystal oscillator and the reference frequency divider ratio set in byte 4 (control byte): fr = crystal oscillator frequency / reference divider ratio.

The reference frequency divider ratio can be set to 1/512, 1/320, and 1/256.

When using a 4-MHz crystal oscillator, fr = 7.8125 kHz, 12.5 kHz, and 15.625 kHz.

The step frequency is 31.25 kHz, 50.0 kHz, and 62.5 kHz.

BYTE 4

Byte 4 is a control byte used to set the different functions. Bit 2 (CP) and controls the output current of the charge-pump circuit. When bit 2 is set to [0], the output current is set to $\pm 55 \mu\text{A}$; when it is set to [1], it is $\pm 250 \mu\text{A}$.

Bit 3 (T2), bit 4 (T1), and bit 5 (T0) are used to set the phase comparator reference signal output and counter divider output in test mode. (For details of test mode, see the test mode setting table.)

Bit 6 (Rsa) and bit 7 (Rsb) are used to set the crystal reference frequency divider ratio. (For details of the crystal reference frequency divider ratio, see the table for crystal reference frequency divider ratios.)

Bit 8 (OS) is used to set the charge-pump driver amplifier output setting. When bit 8 is set to [0], the output is ON (the normal setting used); when it is set to [1], the output is OFF (charge pump is sink mode).

BYTE 5

Byte 5 is used to set the test mode and control the output ports (Band 1 ~ Band 4).

When an output port is set to [0], it is OFF; when it is set to [1], it is ON.

Bandswitch setting is also used to switch between the VHF and UHF bands.

- When the bandswitch data for either B1 or B2 is [1], VHF mode is effective.
- When the bandswitch data for both B1 and B2 is [0], UHF mode is effective.

Set the following maximum values for currents to the bandswitch driver. Ensure also that the total band current is within 17 mA when two bands are operating at the same time.

- Band 1 (pin 4) output current: 7 mA (maximum)
- Band 2 (pin 5) output current: 10 mA (maximum)
- Band 3 (pin 6) output current: 3 mA (maximum)
- Band 4 (pin 7) output current: 7 mA (maximum)

B) READ MODE (Status Request)

When Read Mode is set, power-on reset operation status and phase comparator lock detector output status are output to the master device.

Bit 1 (POR) indicates the power-on reset operation status. When the power supply of Vcc stops, this bit is set to [1]. The conditions for reset to [0] are that voltage supplied to Vcc is 3V or higher, that transmission is requested in READ MODE, and that the status is output. (When Vcc is turned on, bit 1 is also set to [1].)

Bit 2 (FL) indicates the phase comparator lock status. When this is locked, [1] is output; when it is unlocked, [0] is output.

DATA FORMAT
A) WRITE MODE

		MSB							LSB	
1	Address Byte	1	1	0	0	0	MA1	MA0	R/W = 0	ACK
2	Divider Byte 1	0	N14	N13	N12	N11	N10	N9	N8	ACK
3	Divider Byte 2	N7	N6	N5	N4	N3	N2	N1	N0	ACK (L)
4	Control Byte	1	CP	T2	T1	T0	Rsa	Rsb	OS	ACK (L)
5	Band SW Byte	X	X	X	X	B4	B3	B2	B1	ACK (L)

X :DON'T CARE
ACK :Acknowledged
(L) :Latch and transfer timing

B) READ MODE

		MSB							LSB	
1	Address Byte	1	1	0	0	0	MA1	MA0	R/W=1	ACK
2	Status Byte	POR	FL	1	1	1	1	1	1	-

ACK :Acknowledged

DATA SPECIFICATIONS

●MA1, MA0 : programmable hardware address bits

MA1	MA0	ADDRESS PIN APPLIED VOLTAGE
0	0	0 to 0.1Vcc
0	1	OPEN or 0.2Vcc to 0.3Vcc
1	0	0.4Vcc to 0.6Vcc
1	1	0.9Vcc to Vcc

●N14 – N0 : programmable counter data

● CP : charge pump output current setting

[0] : ± 55 μA (typ.)

[1] : ± 250 μA (typ.)

●T2, T1, T0 : test mode setting bits

CHARACTERISTIC		T2	T1	T0	NOTE
Normal operation		0	0	X	-
Charge-pump	OFF	0	1	X	Charge pump is OFF (check output: NF)
	SINK	1	1	0	Only charge pump sink current is ON (check output: NF)
	SOURCE	1	1	1	Only charge pump source current is ON (check output: NF)
Reference signal output		1	0	0	Reference signal output (check output: Band 4)
1/2 counter divider output		1	0	1	1/2 counter output (check output: Band 2)

X :DON'T CARE

Note 6: Testing of the counter divider output requires the input of programmable counter data.

●Rsa, Rsb: Reference frequency divider ratio select bit.

Rsa	Rsb	DIVIDER RATIO	COMPARE FREQUENCY	STEP FREQUENCY
1	1	1/256	15.265kHz	62.5kHz
0	1	1/512	7.8125kHz	31.25kHz
X	1	1/320	12.5kHz	50kHz

●OS: tuning amplifier control bit

- [0] : tuning amplifier ON (normal operation)
- [1] : tuning amplifier OFF (charge pump is sink mode)

●B4, B3, B2, B1: Band output port control and band change control bit

- [0] : band output driver ON
- [1] : band output driver OFF

Band	B4	B3	B2	B1
VHF Band	X	X	0	1
VHF Band	X	X	1	0
UHF Band	X	X	0	0

When the bandswitch data is [1] for either B1 or B2, VHF mode is effective.
 When the bandswitch data is [0] for both B1 and B2, UHF mode is effective.

●POR: power-on reset flag

- [0] : normal operation
- [1] : reset operation

●FL: lock detect flag

- [0] : unlocked
- [1] : locked

●X : don't care

-EXAMPLE OF BUS DATA TRANSMITTER-

S: Start
 ADR: Address Byte
 DIV1: Divider Byte 1 (frequency data)
 DIV2: Divider Byte 2 (frequency data)
 CONT: Control Byte
 BAND: Bandswitch Byte
 A: Acknowledge
 P: Stop

[1] Transmitter - 1

S	ADR	A	DIV1	A	DIV2	A	CONT	A	BAND	A	P
---	-----	---	------	---	------	---	------	---	------	---	---

[2] Transmitter - 2

S	ADR	A	CONT	A	BAND	A	DIV1	A	DIV2	A	P
---	-----	---	------	---	------	---	------	---	------	---	---

[3] Transmitter - 3 (This can be applied if control data and bandswitch data have already been programmed.)

S	ADR	A	DIV1	A	DIV2	A	P
---	-----	---	------	---	------	---	---

[4] Transmitter - 4 (This can be applied if frequency data have already been programmed.)

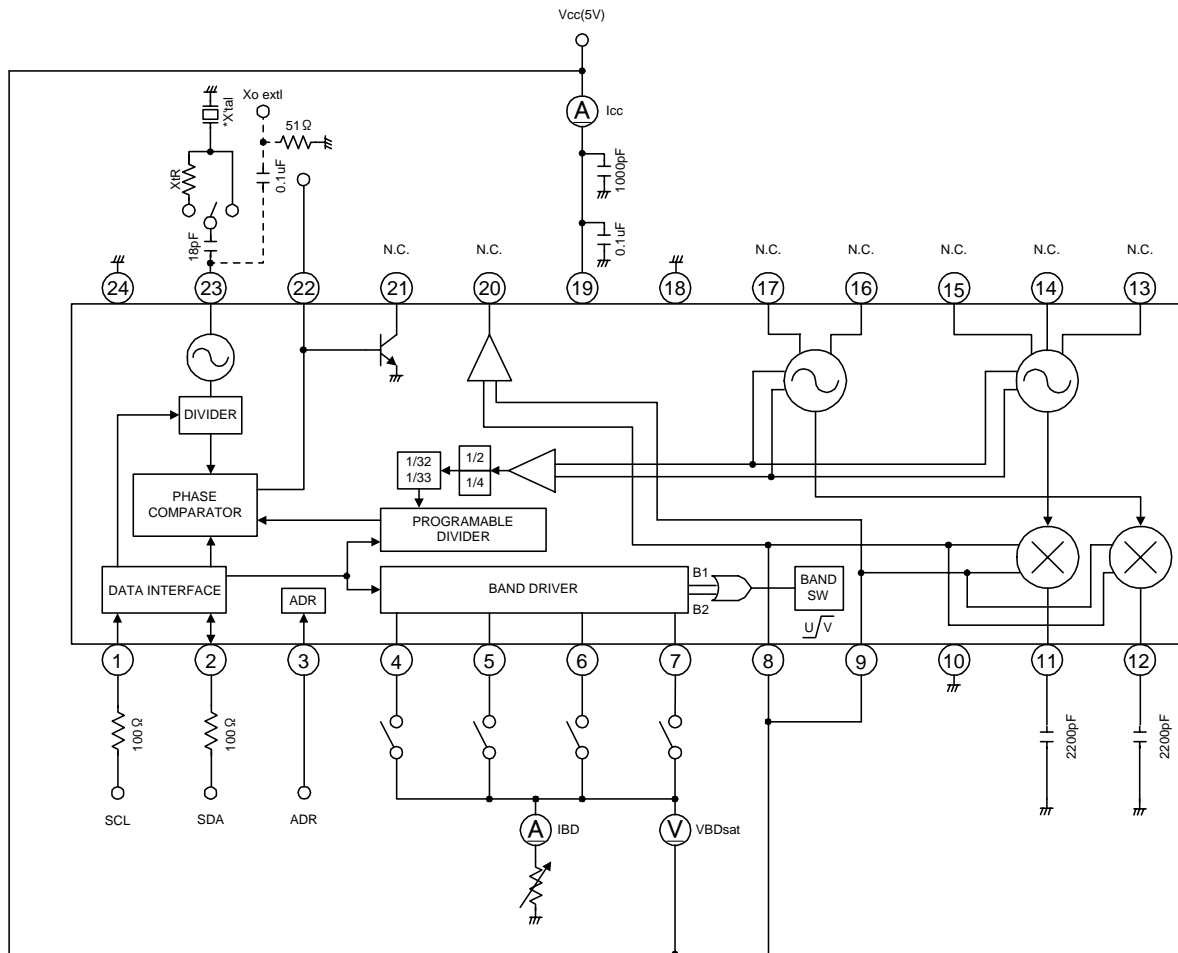
S	ADR	A	CONT	A	BAND	A	P
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[5] Transmitter - 5 (This can be applied if frequency counter data and bandswitch data have already been programmed.)

S	ADR	A	CONT	A	P
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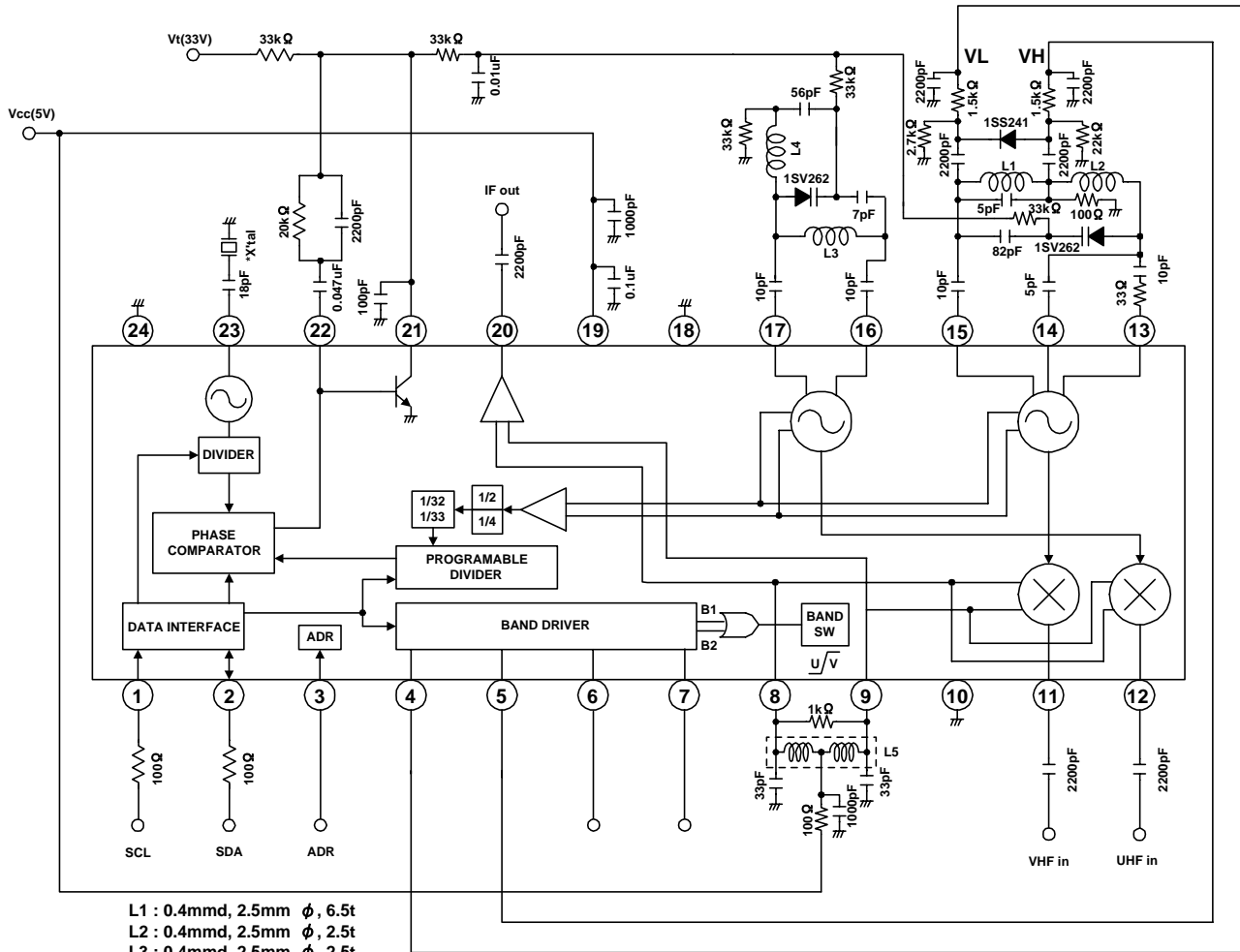
Until the I²C-bus STOP condition is detected, it is possible to input the additional data without transmitting the address data again. (For example: Frequency sweep is possible with additional frequency data.)
 If data transmission is aborted, data programmed before the abort are valid.

TEST CIRCUIT 1



*X'tal: 4MHz (NDK:AT-51)

TEST CIRCUIT 2



L1 : 0.4mmd, 2.5mm ϕ , 6.5t
 L2 : 0.4mmd, 2.5mm ϕ , 2.5t
 L3 : 0.4mmd, 2.5mm ϕ , 2.5t
 L4 : 0.4mmd, 1.5mm ϕ , 1.5t
 L5 : TOKO (886BNF-0357)

*X'tal: 4MHz (NDK:AT-51)

Measurement bus data setting

- Charge pump: High [250 μ A (typ.)]
- Frequency step: 62.5 kHz

TEST CIRCUIT 3

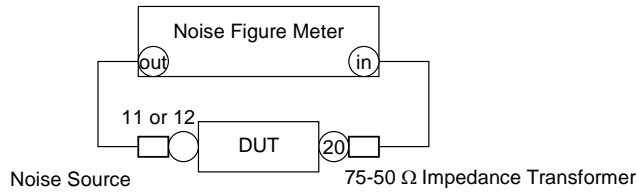


Figure 2: Noise Figure measurement

TEST CIRCUIT 4

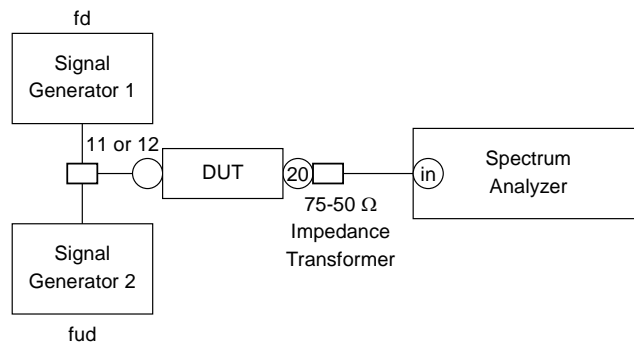
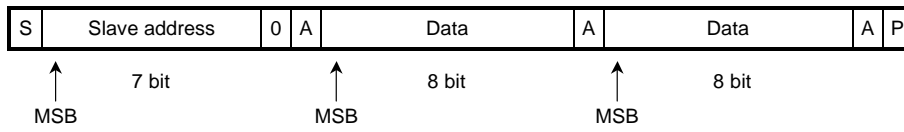


Figure 3: CM / IM3 / 6-ch beat measurement

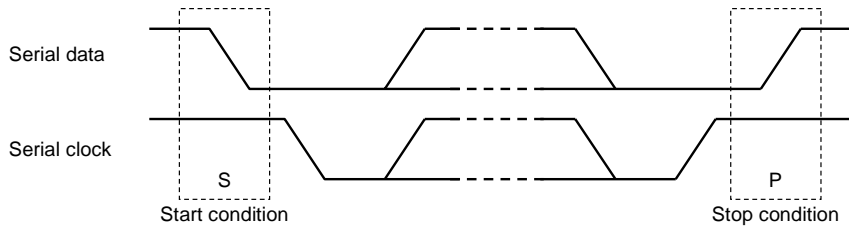
I²C BUS CONTROL SUMMARY

Data transmission format

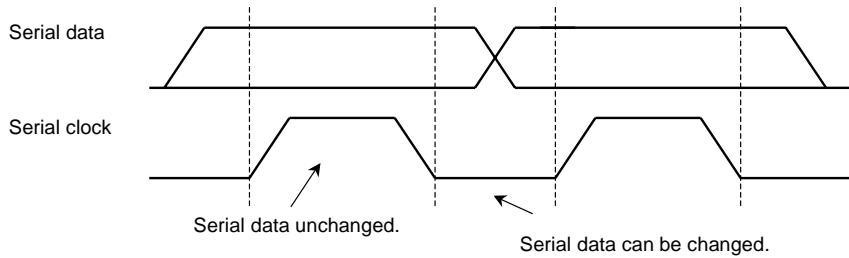


S: Start condition
 P: Stop condition
 A: Acknowledge

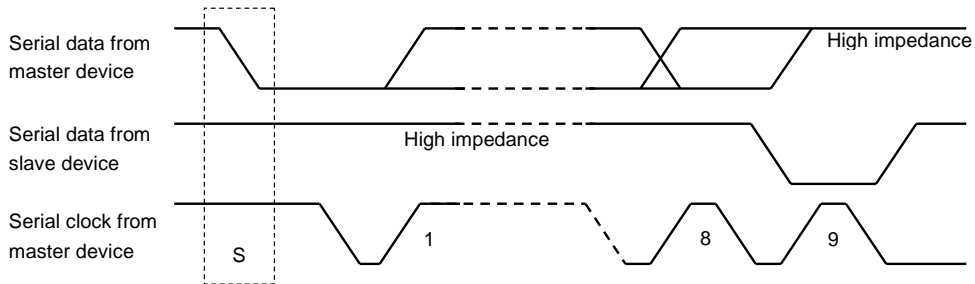
(1) Start / stop conditions



(2) Bit transfer



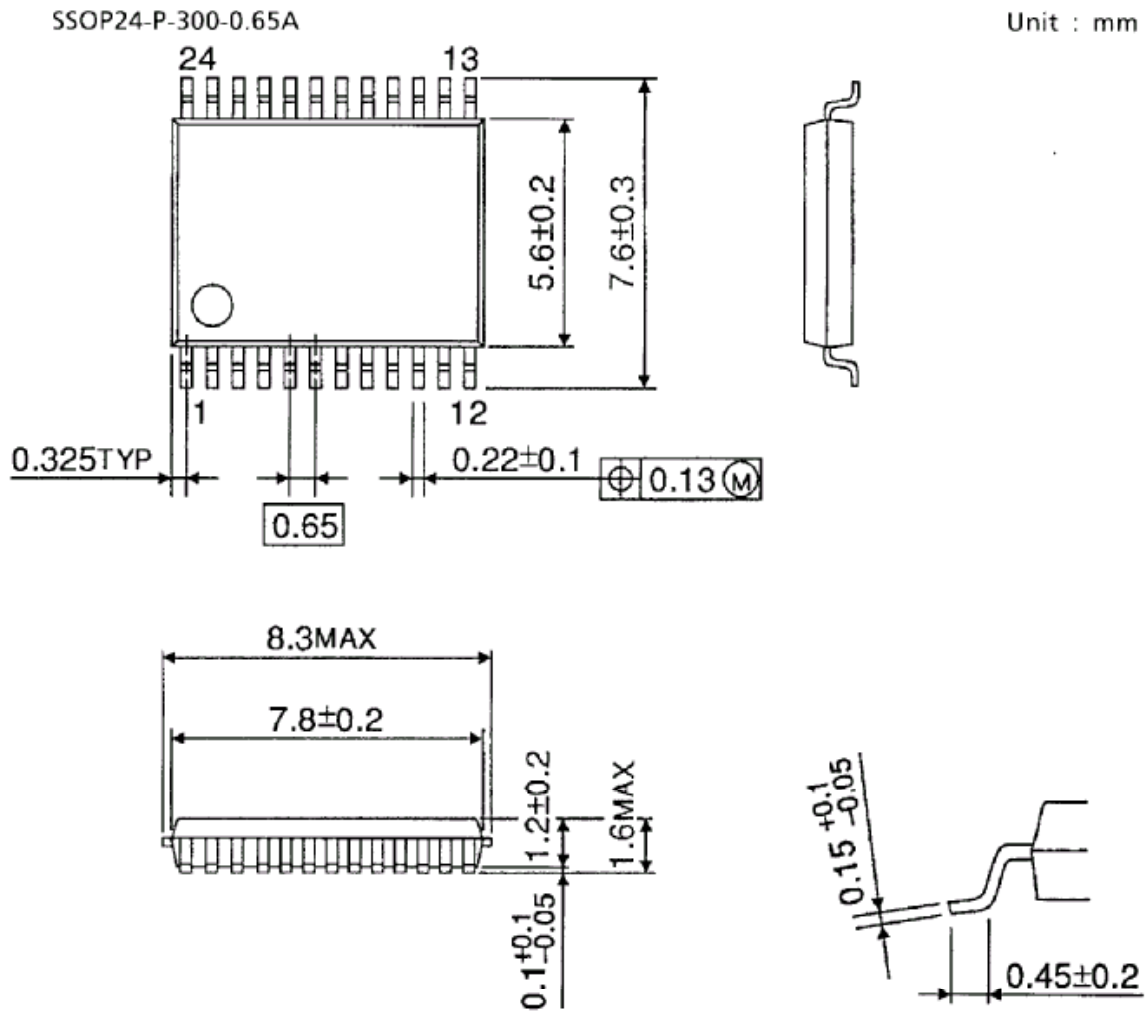
(3) Acknowledge



(4) Slave address

A6	A5	A4	A3	A2	A1	A0	R/W
1	1	0	0	0	*	*	0

PACKAGE DIMENSIONS



Weight: 0.09 g (typ.)

HANDLING PRECAUTIONS

1. The device should not be inserted into or removed from the test apparatus while the voltage is being applied; otherwise breakdown or deterioration in performance of the device may result.

Also, avoid any abrupt increasing or decreasing of the voltage.

Overshoot or chattering of the power supply may cause the IC to be degraded.

To avoid this problem, equip the power supply line with filters.

2. The peripheral circuits described in this datasheet are given only as system examples for evaluating the performance of the device. Toshiba neither recommend the configuration or related values of the peripheral circuits nor intend to manufacture such application systems in large quantities.

Please note that the high-frequency characteristics of the device may vary depending on the external components, mounting method and other factors relating to the application design. Therefore it is the responsibility of users incorporating the device into their designs to evaluate the characteristics of application circuits.

Toshiba only guarantee the quality and characteristics of the device as described in this datasheet and do not assume any responsibility for the customer's application design.

3. In order better to understand the quality and reliability of Toshiba semiconductor products and to incorporate them into designs in an appropriate manner, please refer to the latest Semiconductor Reliability Handbook (Integrated Circuits) published by Toshiba Semiconductor Company.

The handbook can also be viewed online at " <http://www.semicon.toshiba.co.jp/> "

Solderability

Regarding solderability, the following conditions have been confirmed.

- (1) Use of Sn-63Pb solder bath
 - Solder bath temperature = 230(C degree C)
 - Dipping time = 5 seconds
 - The number Number of times = once
 - Use of R-type flux
- (2) Use of Sn-3.0Ag-0.5Cu solder bath
 - Solder bath temperature = 245°C
 - Dipping time = 5 seconds
 - Number of times = once
 - Use of R-type flux

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030619EBA

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